Product / Package Information

Package	MSOP_EP
Body Size	
LeadCount	8
Terminal Finish	100 Sn

Environmental Compliance Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
JIG Material Content Compliant	Level A and B Compliant

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	1.11 E-02	87.7	877000	44.29	442945
Thermosets	Epoxy Resin	Proprietary	6.35 E-04	5.0	50000	2.53	25253
Thermosets	Phenol Resin	Proprietary	6.35 E-04	5.0	50000	2.53	25253
Thermosets	Epoxy Cresol Novolac	29690-82-2	2.54 E-04	2.0	20000	1.01	10101
Other inorganic materials	Carbon Black	1333-86-3	3.81 E-05	0.3	3000	0.15	1515
Subtotal			1.27 E-02	100	1000000	50.51	505069

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	9.76 E-03	97.57	975706	38.80	387991
Copper & its alloys	Iron	7439-89-6	2.28 E-04	2.28	22789	0.91	9062
Copper & its alloys	Zinc	7440-66-6	1.26 E-05	0.13	1263	0.05	502
Copper & its alloys	Phosphorus	7723-14-0	2.42 E-06	0.02	242	0.01	96
Subtotal			1.00 E-02	100.00	1000000	39.77	397652

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.01 E-04	100.0	1000000	0.40	4017

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	6.55 E-04	100.0	1000000	2.61	26054

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	3.10 E-04	99.99	1000000	1.23	12327

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	1.00 E-03	100.0	1000000	3.98	39769

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	3.04 E-04	80	800000	1.21	12090
Thermosets	Epoxy Resin	Proprietary	5.70 E-05	15	150000	0.23	2267
Others	Curing agent & hardener	Proprietary	1.90 E-05	5	50000	0.08	756
Subtotal			3.80 E-04	100	1000000	1.51	15112

	Weight (g)	Percentage (%)	PPM
Package Totals	**2.51 E-02**	**100.00**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability
any inaccuracy of such information.

ANALOG DEVICES

ADI Proprietary